

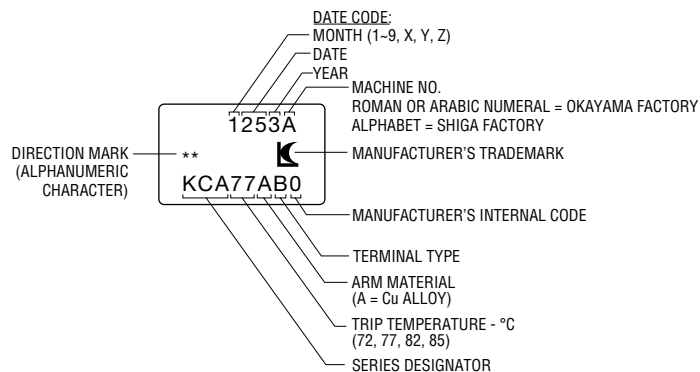
KCA Series A-Type Breaker (Thermal Cutoff Device)

BOURNS®

Wiring Recommendations

This is not a surface mount device for reflow soldering. Therefore, Ni tab wiring should be accomplished by either resistance or laser welding. Solder connections should be avoided.

Typical Part Marking



Standard Packaging Specifications

Plastic Bag.....	1,000 pcs. (fixed)
Inner Box	4,000 pcs. (fixed)
Outer Box	40,000 pcs. max. (up to 10 inner boxes)

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Specifications are subject to change without notice.

The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time. Users should verify actual device performance in their specific applications.

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Caution when using Breaker

Before using the breaker, please fully read the *DESIGN AND HANDLING CAUTIONS* stated below to avoid breaker performance deterioration and/or damage to the breaker body or terminal.

DESIGN CAUTIONS

1. Use within the electrical ratings specified in this data sheet. If used over the rating of voltage or current, ON-OFF life might be impacted and contact may deteriorate due to breaker arm damage.
2. If used over the electrical rating, the circuit may not open safely or operate properly. Please test your device for any abnormalities and confirm that the breaker will open the circuit safely in your device.
3. Mount the breaker on your device where heat is the highest in order to transfer it effectively to the breaker.
4. If the breaker is affixed with an adhesive (resin, etc.), fully test, evaluate and verify that the adhesive presents no negative effects on the breaker before proceeding.
5. After the breaker is mounted, affix it so that the breaker body and terminals will not move. If not affixed properly, breaker resistance could increase or contact could open due to stress during handling or vibration/shock during transportation.
6. Mount the breaker body and terminals in a straight and flat direction. If the body and terminals are mounted in a twisted condition, breaker resistance could increase or create body damage.
7. If breaker is to be resin-molded, test and evaluate the application to determine whether the breaker can be used effectively.
8. The breaker cannot be used as a repetitive ON-OFF thermostat.
9. The breaker is not washable. Do not wash.
10. The breaker is not designed or warranted for flow, reflow or hand-soldering applications. If such application is required, you will need to evaluate whether the breaker is suitable for your specific application.
11. When mounting and after mounting the breaker, do not apply supersonic vibration. Vibration and heat may cause breaker resistance to increase or may cause body damage. If you plan to apply supersonic vibration after mounting the breaker, you will need to evaluate whether the breaker is suitable for your specific application. The breaker is not designed or warranted to withstand supersonic vibration.
12. Do not use the breaker in the following environments:
 - a) Water, oil, chemicals or organic solutions
 - b) Direct sunlight, outdoor exposure, dust
 - c) Dew condensation, allowing the breaker to get wet
 - d) Salt breeze, chlorine, hydrogen sulfide, ammonium, sulfide-oxidation, hydrogen chloride, and anywhere there is a possibility of generating corrosive gas such as sulfurous acid gas
 - e) Strong static electric charge or electromagnetic wave
13. The breaker is not designed or tested for, and should not be used in, aerospace, airplane, nuclear, military, life-sustaining medical and other related applications.

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